



BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	40.0000 mm x 45.0000 mm		
Min track/spacing:	0.0900 mm / 0.0900 mm	Min hole diameter:	0.1000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

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Sheet: File: IoTGW_Isolation.kicad_pcb		
Title: IoTGW Galvanic Isolation		
Size: A4	Date: 2025-01-24	Rev: v2.0.0
KiCad E.D.A. 8.0.4		Id: 1/1